Materials Declaration

Package	LQFP
Body Size	7 X 7
LeadCount	64
Option	Pb Free

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy resin	8	4.94 E-03	35444
SiO2 Filler	86	5.32 E-02	381026
Phenol Resin	5	3.09 E-03	22153
Antimony_Sb2O3	0.4	2.47 E-04	1772
Brominated Resin	0.4	2.47 E-04	1772
Carbon Black	0.2	1.24 E-04	886

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	5.00 E-02	358593
Ni	3	1.56 E-03	11183
Si	0.65	3.38 E-04	2423
Mg	0.15	7.80 E-05	559

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	8.00 E-04	5735

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	3.33 E-03	23895

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.21 E-03	8674

Chip

	% of Chip	Weight (g)	PPM
Si	100	1.85 E-02	132734

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	26	4.77 E-04	3419
Ag Filler	74	1.36 E-03	9732

Molding Compound

Item	PPM	Method
Pb	<2.0	EPA method #3052 (ICPAES)
Cd	<2.0	BS EN 1122:2001B (ICP AES)
Hg	<2.0	Mercury Analyser
Cr+6	<2.0	EPA method #3060A(UV)
PBB	ND	SGS in-house Method by GC/MS
PBDE	ND	SGS in-house Method by GC/MS

Die Attach Paste

Item	PPM	Method
Pb	<5.0	ICP-AES
Cd	<5.0	ICP-AES
Hg	<5.0	ICP-AES
Cr+6	<5.0	EPA method 7196A & EPA 3060A

Package Totals

Weight (g)	PPM
1.40 E-01	1000000

STS-ST-D

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES

ADI Proprietary

07/19/04

Materials Declaration

Package	LQFP
Body Size	7 X 7
LeadCount	64
Option	Sn/Pb

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy resin	8	4.94 E-03	35444
SiO2 Filler	86	5.32 E-02	381026
Phenol Resin	5	3.09 E-03	22153
Antimony_Sb2O3	0.4	2.47 E-04	1772
Brominated Resin	0.4	2.47 E-04	1772
Carbon Black	0.2	1.24 E-04	886

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	5.00 E-02	358593
Ni	3	1.56 E-03	11183
Si	0.65	3.38 E-04	2423
Mg	0.15	7.80 E-05	559

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	8.00 E-04	5735

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	2.83 E-03	20310
Pb	15	5.00 E-04	3584

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.21 E-03	8674

Chip

	% of Chip	Weight (g)	PPM
Si	100	1.85 E-02	132734

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	26	4.77 E-04	3419
Ag Filler	74	1.36 E-03	9732

Molding Compound

Item	PPM	Method
Pb	<2.0	EPA method #3052 (ICPAES)
Cd	<2.0	BS EN 1122:2001B (ICP AES)
Hg	<2.0	Mercury Analyser
Cr+6	<2.0	EPA method #3060A(UV)
PBB	ND	SGS in-house Method by GC/MS
PBDE	ND	SGS in-house Method by GC/MS

Die Attach Paste

Item	PPM	Method
Pb	<5.0	ICP-AES
Cd	<5.0	ICP-AES
Hg	<5.0	ICP-AES
Cr+6	<5.0	EPA method 7196A & EPA 3060A

Package Totals

Weight (g)	PPM
1.40 E-01	1000000

STS-ST-E

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ANALOG DEVICES

ADI Proprietary

07/19/04